

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Cancelled)

2. (Currently amended) The method for manufacturing circuit devices as set forth in Claim [1] ~~5~~ further comprising forming a block that includes a plurality of the mounting portions arranged in a matrix form, wherein performing resin sealing comprises covering a plurality of circuit elements, each circuit element being coupled to one of the mounting portions.

3. (Currently amended) ~~The method for manufacturing circuit devices as set forth in Claim 4,~~

A method for manufacturing circuit devices, the method comprising:  
forming conductive patterns on a planar body, wherein the planar body is a conductive foil ,~~the conductive foil having a surface provided with~~ and the conductive patterns are formed in a convex shape by separation grooves, the conductive patterns forming mounting portions for circuit elements;

disposing a circuit element on at least one of the mounting portions;  
bringing a backface of the planar body into contact with a lower mold having air vents to define a resin injection cavity above the planar body and air release passages that extend beneath the planar body, wherein the air release passages are at least partially formed from the backface of the planar body and the air vents;

sealing a surface of the planar body with an insulating resin so that the circuit element is covered therewith; and

separating each mounting portion.

4. (Canceled)

5. (Currently amended) The method for manufacturing circuit devices as set forth in Claim

4, A method for manufacturing circuit devices, the method comprising:

forming conductive patterns on a planar body, the conductive patterns forming mounting portions for circuit elements;

disposing a circuit element on at least one of the mounting portions;

bringing a backface of the planar body into contact with a lower mold having wherein the air vents are disposed in parallel to define a resin injection cavity above the planar body and air release passages that extend beneath the planar body, wherein the air release passages are at least partially formed from the backface of the planar body and the air vents;

sealing a surface of the planar body with an insulating resin so that the circuit element is covered therewith; and

separating each mounting portion.

6. (Previously Presented) The method for manufacturing circuit devices as set forth in Claim 5, wherein an air vent provided at a central part is formed to be larger than an air vent provided at a peripheral part.

7-8. (Canceled)

9. (Currently amended) The method for manufacturing circuit devices as set forth in Claim 4, A method for manufacturing circuit devices, the method comprising:

forming conductive patterns on a planar body, the conductive patterns forming mounting portions for circuit elements;

disposing a circuit element on at least one of the mounting portions;

bringing a backface of the planar body into contact with a lower mold having air vents to define a resin injection cavity above the planar body and air release passages that extend beneath the planar body, wherein the air release passages are at least partially formed from the backface of the planar body and the air vents;

sealing a surface of the planar body with an insulating resin so that the circuit element is covered therewith; and

separating each mounting portion,

wherein a plurality of blocks are aligned, in each block the conductive patterns form a plurality of mounting portions arranged in a matrix form on the planar body.

10. (Original) The method for manufacturing circuit devices as set forth in Claim 9, wherein the insulating resin is formed by simultaneously subjecting all of the blocks of the conductive foil to transfer molding.

11. (Currently amended) The method for manufacturing circuit devices as set forth in Claim [[1]] 5, wherein the air vent strides over a peripheral part of the cavity and is extended from inside the cavity to an outer part of the cavity.

12. (Currently amended) The method for manufacturing circuit devices as set forth in Claim [[1]] 5 wherein bringing the backface of the planar body into contact with the lower mold having air vents comprises bringing the backface of the planar body into contact with at least one of the air vents.

13. (Previously Presented) The method for manufacturing circuit devices as set forth in Claim 12 wherein bringing the backface of the planar body into contact with at least one of the air vents comprises enabling the release of air through the air vent from between the planar body and the lower mold.

14. (Currently amended) ~~The method for manufacturing circuit devices as set forth in Claim 42~~

A method for manufacturing circuit devices, the method comprising:  
forming conductive patterns on a planar body, the conductive patterns forming mounting  
portions for circuit elements;

disposing a circuit element on at least one of the mounting portions;

bringing a backface of the planar body into contact with a lower mold having air vents to define a resin injection cavity above the planar body and air release passages that extend beneath the planar body, wherein the air release passages are at least partially formed from the backface of the planar body and the air vents, wherein bringing the backface of the planar body into contact with the lower mold having air vents comprises bringing the backface of the planar body into contact with at least one of the air vents and sealing at least one of the air vents with the backface of the planar body;

sealing a surface of the planar body with an insulating resin so that the circuit element is covered therewith; and

separating each mounting portion.